

## **Notification about the transfer of the semiconductor business**

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

**Nuvoton Technology Corporation Japan**

# SK840303

## Silicon N-channel MOS FET

For DC-DC converter circuits

### ■ Overview

SK840303 is the N-channel MOS FET that is highly suitable for DC-DC converter and other switching circuits.

### ■ Features

- Low drain-source ON resistance:  $R_{DS(on)}$  typ. = 6 m $\Omega$  ( $V_{GS} = 4.5$  V)
- Small package with back side heat sink for improved heat dissipation.
- Eco-friendly Halogen-free package

### ■ Packaging

SK8403030L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	$V_{DSS}$	33	V
Gate-source surrender voltage	$V_{GSS}$	$\pm 20$	V
Drain current	$I_D$	22	A
Peak drain current *1,2	$I_{DP}$	66	A
Power dissipation	$P_D$	$T_C = 25^\circ\text{C}$	28
		$t = 10$ s *1,2	2
Repetitive peak avalanche current *3	$I_{AR}$	22	A
Avalanche energy capability *4	EAS	50	mJ
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*1: Mounted on a glass epoxy PC board: 25.4 mm  $\times$  25.4 mm  $\times$  0.8 mm

\*2: Pulse measurement: Channel temperature not to exceed 150 $^\circ\text{C}$

\*3:  $V_{DD} = 24$  V,  $V_{GS} = 10$  V  $\rightarrow$  0 V,  $L = 0.1$  mH,  $T_{ch} = 25^\circ\text{C}$  (initial)

\*4:  $V_{DD} = 24$  V,  $V_{GS} = 10$  V  $\rightarrow$  0 V,  $L = 0.1$  mH,  $I_{AR} = 15$  A,  $T_{ch} = 25^\circ\text{C}$  (initial)

### ■ Package

#### • Code

HSS08-F1-B

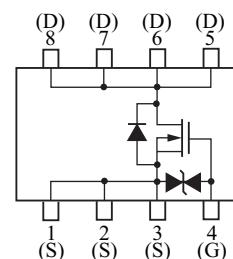
Package dimension clicks here.  $\rightarrow$

#### • Pin Name

1: Source	5: Drain
2: Source	6: Drain
3: Source	7: Drain
4: Gate	8: Drain

### ■ Marking Symbol: 03

### ■ Internal Connection

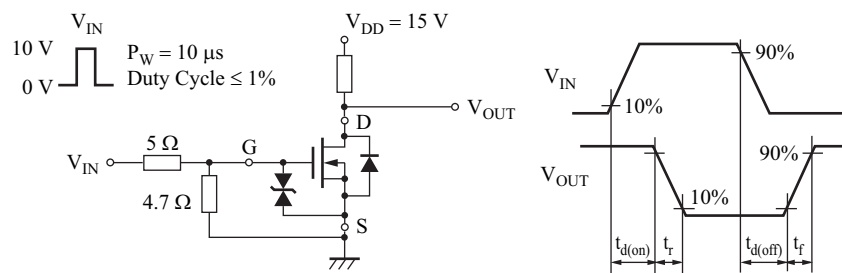


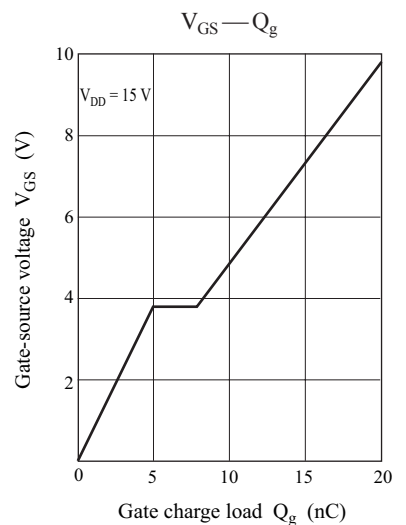
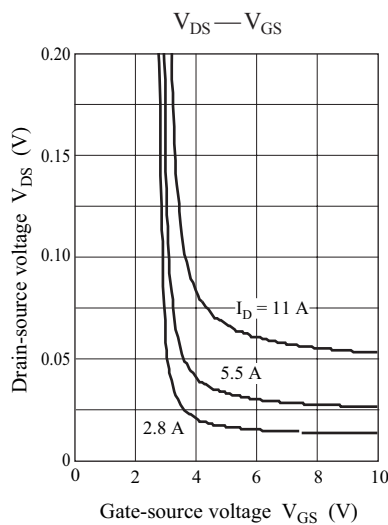
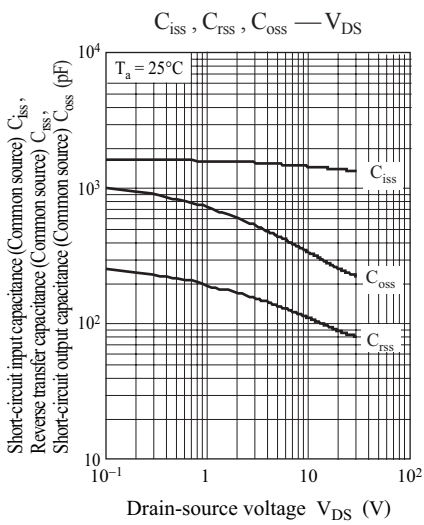
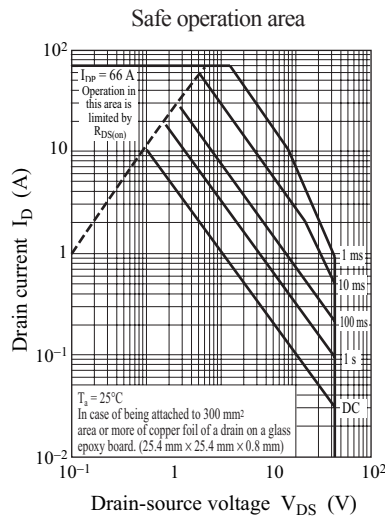
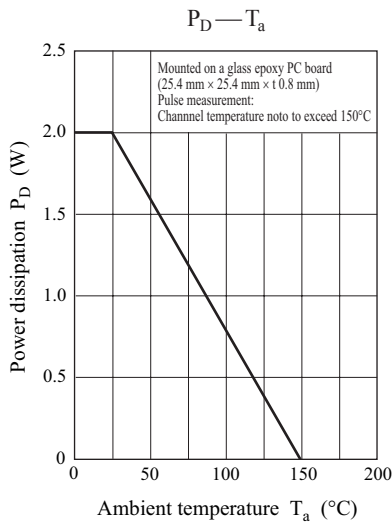
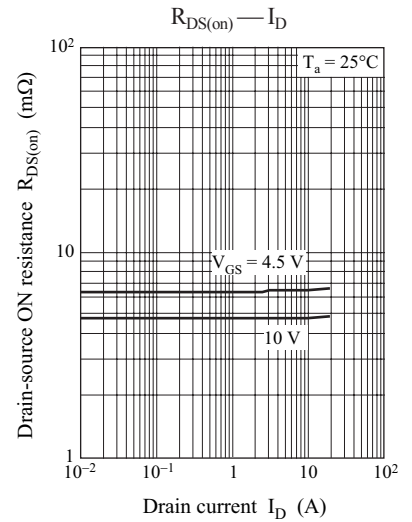
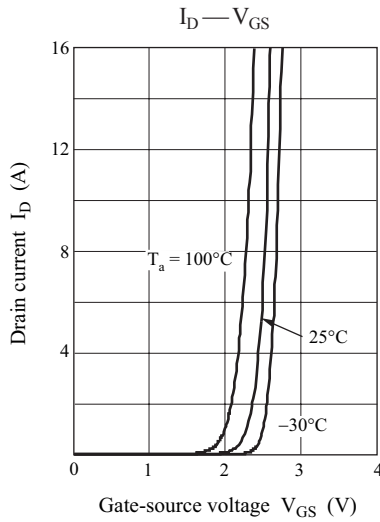
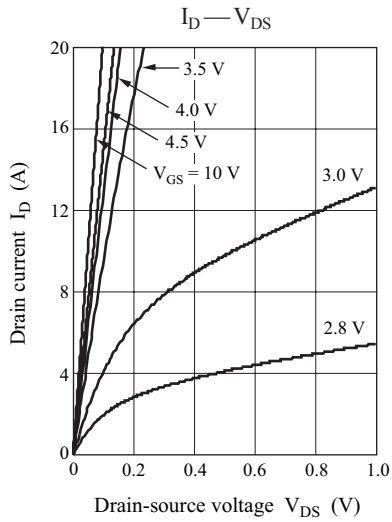
**Electrical Characteristics**  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ 

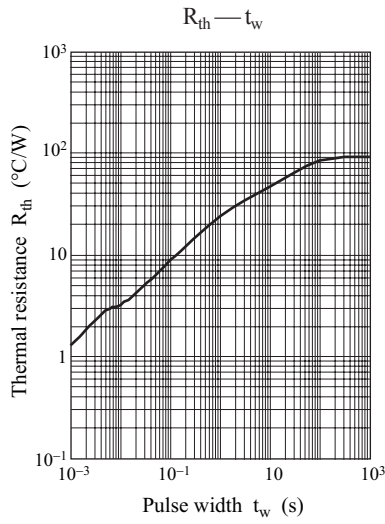
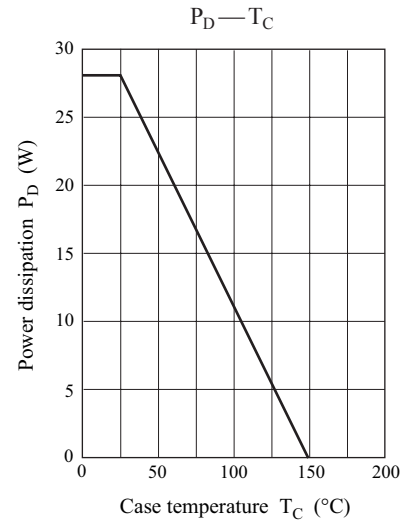
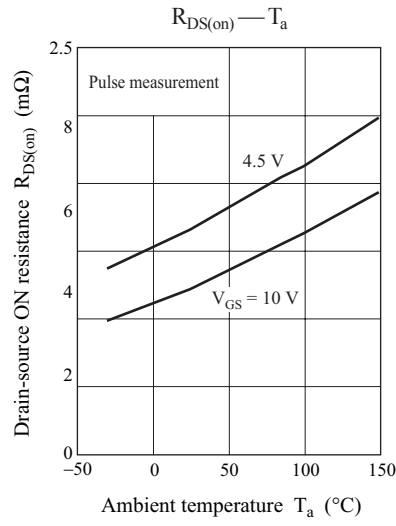
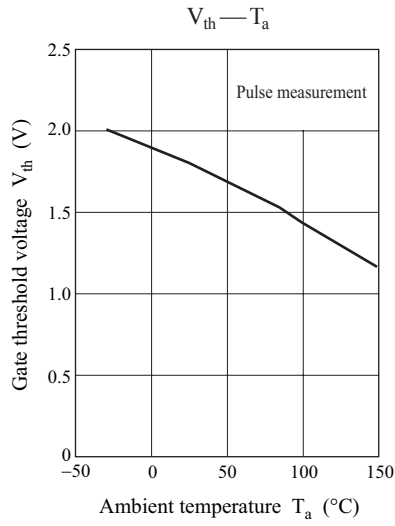
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source surrender voltage	$V_{DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	33			V
Drain-source cutoff current	$I_{DSS}$	$V_{DS} = 33 \text{ V}, V_{GS} = 0 \text{ V}$			10	$\mu\text{A}$
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$			$\pm 10$	$\mu\text{A}$
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 2.3 \text{ mA}, V_{DS} = 10 \text{ V}$	1		2.5	V
Drain-source ON resistance	$R_{DS(on)}$	$I_D = 11 \text{ A}, V_{GS} = 10 \text{ V}$		4	6	m $\Omega$
		$I_D = 11 \text{ A}, V_{GS} = 4.5 \text{ V}$		6	9	
	$ Y_{fs} $	$I_D = 11 \text{ A}, V_{GS} = 10 \text{ V}$		90		S
<b>Dynamic Characteristics</b>						
Short-circuit input capacitance (Common source)	$C_{iss}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	850	1450	2050	pF
Short-circuit output capacitance (Common source)	$C_{oss}$		190	320	450	pF
Reverse transfer capacitance (Common source)	$C_{rss}$		40	110	180	pF
Signal source resistance	$R_g$	$f = 8 \text{ MHz}$		2.8	5	$\Omega$
Turn-on delay time *	$t_{d(on)}$	$V_{DD} = 15 \text{ V}, V_{GS} = 0 \text{ V to } 10 \text{ V},$ $I_D = 11 \text{ A}$		8		ns
Rise time *	$t_r$			7		ns
Turn-off delay time *	$t_{d(off)}$	$V_{DD} = 15 \text{ V}, V_{GS} = 10 \text{ V to } 0 \text{ V},$ $I_D = 11 \text{ A}$		40		ns
Fall time *	$t_f$			6		ns
Gate charge load	$Q_g$	$V_{DD} = 15 \text{ V}, V_{GS} = 0 \text{ V to } 4.5 \text{ V},$ $I_D = 22 \text{ A}$		10		nC
Gate-source charge	$Q_{gs}$			5		nC
Gate-drain charge	$Q_{gd}$			3		nC
<b>Body diode characteristics</b>						
Drain-source voltage	$V_{SD}$	$I_S = 11 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Measurement circuit







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